

BRLV10100RA
Rev. B May.-2018

TO-220
O03 Tm.06ttky D 79.8T

/ Absolute Maximum Ratings($T_a=25$)

Parameter	Symbol	Rating	Unit
Recurrent Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} , V_{RWM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average forward rectified current	$I_{F(AV)}$	10	A
Non Repetitive Peak Surge Current	I_{FSM}	80	A
Thermal Resistance Junction to Case	R_{Jc}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

/ Electrical Characteristics($T_a=25$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Reverse Voltage	V_{BR}	$I_R=100\mu A(T_a=25)$	100			V
Forward Voltage	V_F	$I_F=1A(T_a=25)$		0.41	0.48	V
		$I_F=3A(T_a=25)$		0.48	0.53	V
		$I_F=1A(T_a=125)$			0.44	V
		$I_F=3A(T_a=125)$			0.50	V
Instantaneous Reverse Current	I_R Note 1	$V_R=100V(T_a=25)$		10	50	A
		$V_R=100V(T_a=125)$			10	mA

/Notes

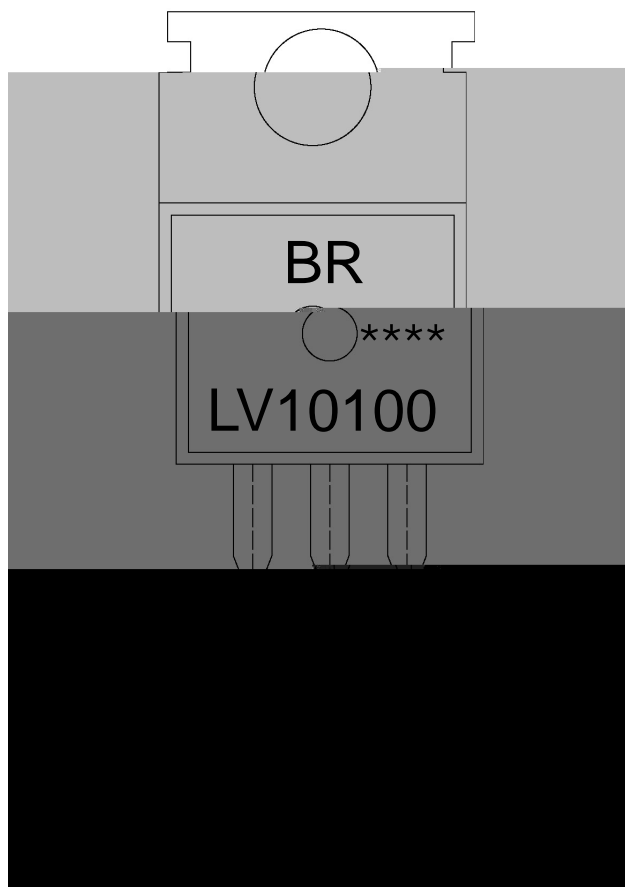
1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

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DATA SHEET

/ Marking Instructions



BR

LV10100

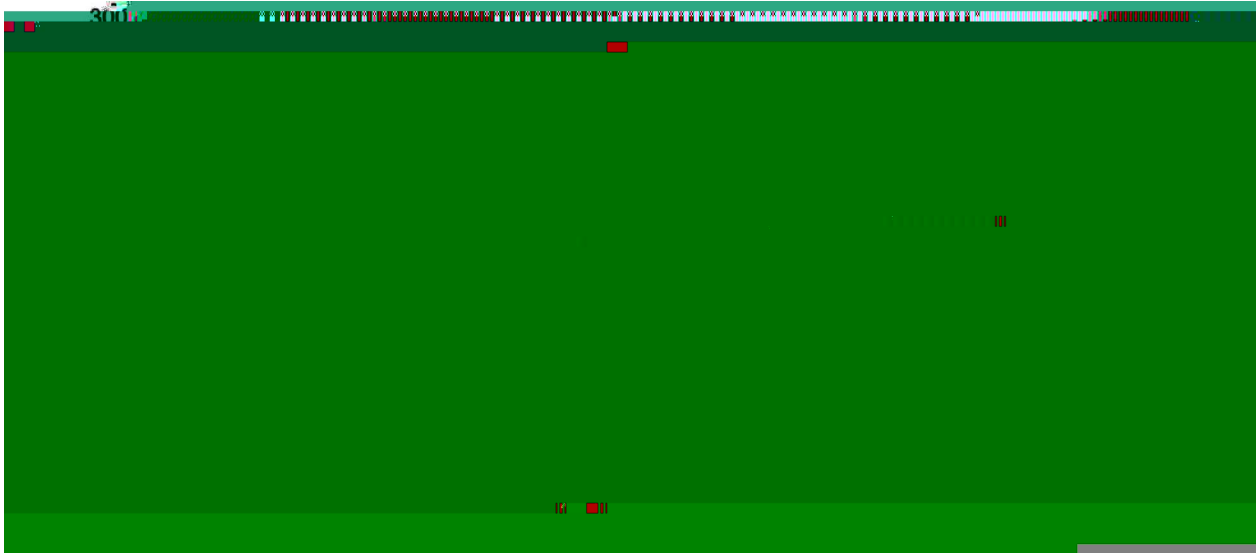
Note:

BR: Company Code

LV10100 Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|-------|-----|-----------|--------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units		Dimension	(unit mm ³)
	Units/Bag /	Bags/Inner Box /		